



Thermal Interface Material X-23-7772-4

PRODUCT DESCRIPTION

Shrinking die and increasing power demands continue to make the thermal solution a critical part of IC package design. Shin-Etsu MicroSi's X-23-7772-4 thermal interface material improves performance by enabling packages to run cooler without sacrificing reliability. The ability of X-23-7772-4 to dissipate heat enables users to reduce the overall cost of their thermal solution. Shin-Etsu MicroSi's X-23-7772-4 is designed to meet current and future thermal management requirements, thus providing drop-in solutions for new IC packages, without the expense of qualifications. This highly thermal conductive gel has been successfully used throughout the semiconductor industry on temperature sensitive components.

PROPERTIES

Property

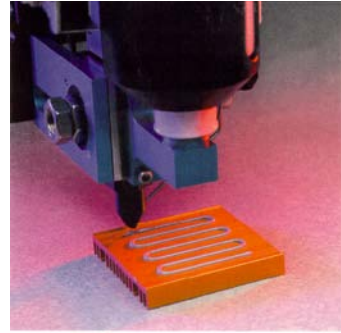
Viscosity (Pascal Second)	176
Appearance	Gray
Bleed (425 °K/24 hr)	0
Volatile Content	< 0.39%
Specific Gravity	2.4
Thermal Conductivity(W/m °K)	3.5

Packaging Description

Thermal Grease X-23-7772-4	60 gm cartridges
is available in:	
Storage Conditions:	-15°C to -35°C
Cure Conditions	125°C/ 90 min

APPLICATION

Shin-Etsu MicroSi can provide X-23-7772-4 in 60gm cartridges. The cartridge delivery system can be utilized with automated equipment to minimize waste and provide an accurate dispense weight. The cartridge delivery system allows dispensing of the material, while protecting the integrity and exposure level of the unused portion.



PERFORMANCE

This curing silicone gel is homogenous with unique fillers that enhance thermal conductivity. X-23-7772-4 is supplied in grease form. When exposed to ambient temperatures the material starts to cure, forming an excellent interface between substrates providing excellent thermal conductivity.

Shin-Etsu MicroSi

Shin-Etsu MicroSi, Inc. is a wholly owned subsidiary of Shin-Etsu Chemical Co., Ltd., a global leader in research, development and the manufacture of chemicals used in the semiconductor industry. From its headquarters in Phoenix, Arizona, Shin-Etsu MicroSi provides high performance products and materials including:

- Thermal Interface Materials
- KJR Liquid Coating Materials
- Contrast Enhancement Materials
- Mask Blanks
- PBN Crucibles
- Photoresists / Developers
- Quartz Substrates & Wafers
- Liquid Underfill Materials
- Barrier Coats
- Pellicles
- Flexible Copper Laminate
- Epoxy Molding Compounds
- Adhesion Promoters

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